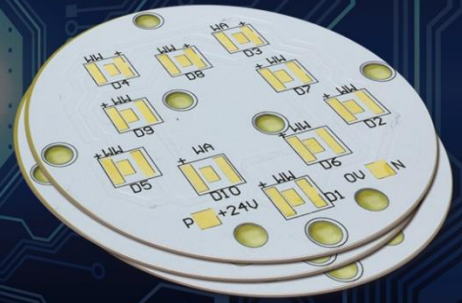


Thermally Set Pad

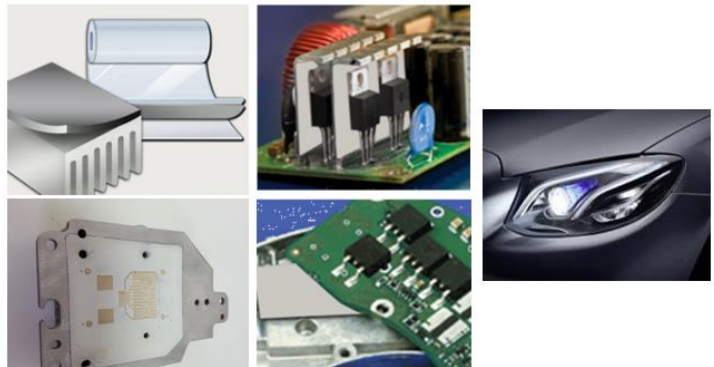


Description

Thermally Set Pad (TSP) is a thermal interface material that combines the advantage of low thermal resistance, electrical isolation, and thermally set properties. Based on the epoxy resin and specific ceramic filler, this product can be used as the adhesive material for an interface assembly used in electronic component manufacturing of LED bulbs, electric motors, power electronics, MOSFET, printed circuit boards, heatsinks and more. Compared with traditional thermal interface materials, TSP provides greater design freedoms, particularly in applications that require adhesion, thinly shaped structures, high reliability, broad operating temperature ranges, and high thermal conductivity. TSP needs to be heated in order to fully cure. Ideal curing conditions: 60 minutes @ 125°C or 45 minutes @ 135°C.

Applications

- Electronic Devices
- Electric Motors/Automotive
- High Brightness LED Module
- Printed Circuit Boards



Features

- Excellent Thermal Conductivity
- Flexible Thickness – low thermal resistivity
- Easy to Process
- Broad Operating Temperature
- Thermally Curing at Elevated Temperature
- Customized Structure available for thin/small designs (e.g. Omni-directional LED bulb)
- RoHS compliant, Halogen free & lead-free process

